

C2220X394F5TACTU

Aliases (C2220X394F5TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.39 uF, 1%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	190 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	2220	
L	5.9mm +/-0.75mm	
W	5mm +/-0.4mm	
Т	1.7mm +/-0.15mm	
S	3.5mm MIN	
В	0.7mm +/-0.35mm	

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S	3.5mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

1000

Packaging

Packaging Quantity

Specifications		
Capacitance	0.39 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	1%	
Voltage DC	50 VDC	
Dielectric Withstanding Voltage	125 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	2.5641 GOhms	

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Insulation Resistance	2.5641 GOhms

T&R, 180mm, Plastic Tape

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